1

SDAS036D - APRIL 1982 - REVISED AUGUST 1995

- 3-State Buffer-Type Outputs Drive Bus **Lines Directly**
- **Bus-Structured Pinout**
- **Package Options Include Plastic** Small-Outline (DW) Packages, Ceramic Chip Carriers (FK), and Plastic (NT) and Ceramic (JT) DIPs

description

These dual 4-bit D-type latches feature 3-state outputs designed specifically for bus driving. These devices are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

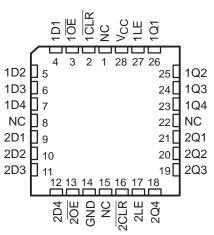
The dual 4-bit latches are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs in true form, according to the function table. When LE is low, the outputs are latched. When the clear (CLR) input goes low, the Q outputs go low independently of LE. The outputs are in the high-impedance state when the output-enable (\overline{OE}) input is at a high logic level.

The SN54ALS873B and SN54AS873A are characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS873B and SN74AS873A are characterized for operation from 0°C to 70°C.

SN54ALS873B, SN54AS873A JT PACKAGE
SN74ALS873B, SN74AS873A DW OR NT PACKAGE
(TOP VIEW)

	•	,	
1CLR 1OE 1D1 [1D2 [1D3 [1D4 [2D1 [2D2 [2D3 [2D4 [2OE]	1 2 3 4 5 6 7 8 9 10 11	18 17 16 15	Vcc 1LE 1Q1 1Q2 1Q3 1Q4 2Q1 2Q2 2Q3 2Q4 2LE
	11	14	·
GND [12	13	2CLR

SN54ALS873B, SN54AS873A ... FK PACKAGE (TOP VIEW)



NC - No internal connection

FUNCTION TABLE (each latch)

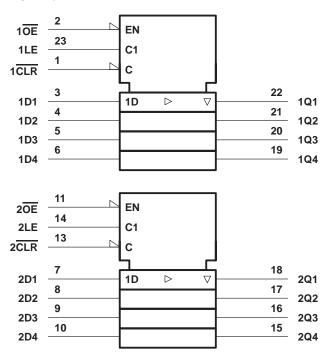
	INPU	JTS		OUTPUT
OE	CLR	LE	D	Q
L	L	Х	Х	L
L	Н	Н	Н	н
L	Н	Н	L	L
L	Н	L	Х	Q ₀
Н	Х	Х	Х	Z

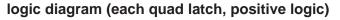
PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

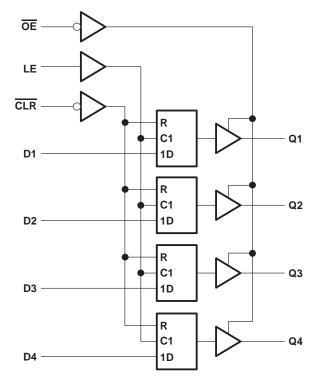
POST OFFICE BOX 1443 • HOUSTON, TEXAS 77251-1443

SDAS036D – APRIL 1982 – REVISED AUGUST 1995

logic symbol[†]







[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the DW, JT, and NT packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V ₁	7V
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54ALS873B	–55°C to 125°C
SN74ALS873B	0°C to 70°C
Storage temperature range	-65°C to 150°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SNS	54ALS87	'3B	SN74ALS873B		'3B	
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-1			-2.6	mA
IOL	Low-level output current			12			24	mA
TA	Operating free-air temperature	-55		125	0		70	°C



SDAS036D - APRIL 1982 - REVISED AUGUST 1995

			SN5	4ALS87	'3B	SN7	4ALS87	'3B	
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX			MAX	UNIT
VIK	V _{CC} = 4.5 V,	II = - 18 mA			-1.2			-1.2	V
	$V_{CC} = 4.5 V \text{ to } 5.5 V,$	I _{OH} = -0.4 mA	V _{CC} -2			V _{CC} -2			
VOH		I _{OH} = -1 mA	2.4	3.3					V
	V _{CC} = 4.5 V	I _{OH} = -2.6 mA				2.4	3.2		
N		I _{OL} = 12 mA		0.25	0.4		0.25	0.4	V
VOL	$V_{CC} = 4.5 V$	I _{OL} = 24 mA					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			20			20	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-20			-20	μΑ
Ц	V _{CC} = 5.5 V,	V _I = 7 V			0.1			0.1	mA
Iн	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
١ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.2			- 0.2	mA
10 [‡]	V _{CC} = 5.5 V,	V _O = 2.25 V	-20		-112	-30		-112	mA
		Outputs high		11	21		11	21	
ICC	V _{CC} = 5.5 V	Outputs low		16	29		16	29	mA
		Outputs disabled		20	31		20	31	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, I_{OS}.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	UNIT
	Dulas duration	CLR low	15		15		
tw	Pulse duration	LE high	10		10		ns
t _{su}	Setup time, data before LE \downarrow		10		10		ns
t _h	Hold time, data after LE \downarrow		7		7		ns



SDAS036D - APRIL 1982 - REVISED AUGUST 1995

switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CL R1 R2	c = 4.5 V = 50 pF, = 500 Ω, = 500 Ω, = MIN to			UNIT
			SN54AL	S873B	SN74AL	S873B	
			MIN	MAX	MIN	MAX	
^t PLH	P	Q	2	23	2	14	
^t PHL	D	Q	2	17	2	14	ns
^t PLH		0	8	31	8	22	
^t PHL	LE	Q	8	26	8	21	ns
^t PHL	CLR	Q	6	27	6	20	ns
^t PZH	ŌĒ	0	4	24	4	18	
tPZL	UE	Q	4	23	4	18	ns
^t PHZ	OE	Q	2	12	2	10	ns
tPLZ	UE	Q	2	30	2	15	115

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage, V _{CC}	
Input voltage, V	
Voltage applied to a disabled 3-state output	
Operating free-air temperature range, T _A : SN54AS873A	–55°C to 125°C
SN74AS873A	0°C to 70°C
Storage temperature range	-65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	SN54AS873A SN74AS873A					
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
IOH	High-level output current			-12			-15	mA
IOL	Low-level output current			32			48	mA
TA	Operating free-air temperature	-55		125	0		70	°C



SDAS036D - APRIL 1982 - REVISED AUGUST 1995

			SN	54AS87	3A	SN	74AS873	3A	
PARAMETER	TEST C	ONDITIONS	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT
VIK	V _{CC} = 4.5 V,	lj = – 18 mA			-1.2			-1.2	V
	V _{CC} = 4.5 V to 5.5 V,	$I_{OH} = -2 \text{ mA}$	V _{CC} -2	2		V _{CC} -2			
VOH		I _{OH} = – 12 mA	2.4	3.2					V
	V _{CC} = 4.5 V	I _{OH} = -15 mA				2.4	3.3		
N/		I _{OL} = 32 mA		0.25	0.5				
V _{OL}	$V_{CC} = 4.5 V$	$I_{OL} = 48 \text{ mA}$					0.35	0.5	V
IOZH	V _{CC} = 5.5 V,	V _O = 2.7 V			50			50	μΑ
IOZL	V _{CC} = 5.5 V,	V _O = 0.4 V			-50			-50	μA
lj	V _{CC} = 5.5 V,	$V_{I} = 7 V$			0.1			0.1	mA
ЧΗ	V _{CC} = 5.5 V,	V _I = 2.7 V			20			20	μΑ
۱ _{IL}	V _{CC} = 5.5 V,	V _I = 0.4 V			- 0.5			- 0.5	mA
۱ ₀ ‡	V _{CC} = 5.5 V,	V _O = 2.25 V	-30		-112	-30		-112	mA
		Outputs high		68	110		68	110	
ICC	$V_{CC} = 5.5 V$	Outputs low		67	109		67	109	mA
		Outputs disabled		80	129		80	129	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

[†] All typical values are at V_{CC} = 5 V, T_A = 25° C.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				S873A	A SN74AS873A		
			MIN	MAX	MIN	MAX	UNIT
. *	w* Pulse duration	CLR low	5		5		
tw*	Pulse duration	LE high	6		5		ns
t _{su} *	Setup time, data before LE \downarrow		2		2		ns
t _h *	Hold time, data after LE \downarrow		4.5		4.5		ns

* On products compliant to MIL-STD-883, Class B, this parameter is based on characterization data but is not production tested.



SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A DUAL 4-BIT D-TYPE LATCHES WITH 3-STATE OUTPUTS SDAS036D – APRIL 1982 – REVISED AUGUST 1995

switching characteristics (see Figure 1)

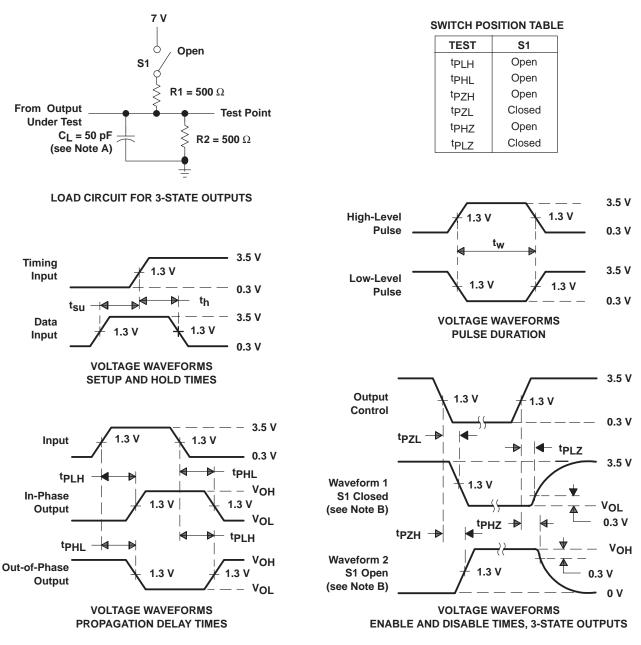
PARAMETER	FROM (INPUT)	TO (OUTPUT)	VC CL R1 R2 TA	UNIT			
			SN54A	S873A	SN74AS873A		
			MIN	MAX	MIN	MAX	
^t PLH	D	0	3	12.5	3	9.5	ns
^t PHL	U	Q	3	8.5	3	7.5	
^t PLH		0	6	15.5	6	13	ns
^t PHL	LE	Q	4	9	4	7.5	
^t PHL	CLR	Q	3	10.5	3	9	ns
^t PZH	ŌĒ	0	2	8	2	6.5	
tPZL	UE	Q	4	11	4	10.5	ns
^t PHZ	OE	Q	2	8	2	7.5	ns
tPLZ	UE	Ŷ	2	8.5	2	7.5	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



SDAS036D - APRIL 1982 - REVISED AUGUST 1995





- NOTES: A. CL includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 1 MHz, Z_O = 50 Ω , t_f \leq 2 ns, t_f \leq 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms





25-Sep-2013

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
84032013A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	Samples
8403201KA	OBSOLETE	E CFP	W	24		TBD	Call TI	Call TI	-55 to 125		
8403201LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	Samples
SN74ALS873BDW	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BDWE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BDWG4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BDWR	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BDWRE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BDWRG4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS873B	Sample
SN74ALS873BNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	Sample
SN74ALS873BNT3	OBSOLETE	E PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SN74ALS873BNTE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS873BNT	Sample
SN74AS873ADW	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ADWR	OBSOLETE	SOIC	DW	24		TBD	Call TI	Call TI	0 to 70		
SN74AS873ANT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI	0 to 70		
SNJ54ALS873BFK	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	84032013A SNJ54ALS 873BFK	Sampl
SNJ54ALS873BJT	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type	-55 to 125	8403201LA SNJ54ALS873BJT	Sample
SNJ54AS873AFK	OBSOLETE	LCCC	FK	28		TBD	Call TI	Call TI	-55 to 125		
SNJ54AS873AJT	OBSOLETE	CDIP	JT	24		TBD	Call TI	Call TI	-55 to 125		



25-Sep-2013

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)		(3)		(4/5)	
SNJ54AS873AW	OBSOLETE	CFP	W	24		TBD	Call TI	Call TI	-55 to 125		

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes. **Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ALS873B, SN54AS873A, SN74ALS873B, SN74AS873A :

Catalog: SN74ALS873B, SN74AS873A

• Military: SN54ALS873B, SN54AS873A



www.ti.com

PACKAGE OPTION ADDENDUM

25-Sep-2013

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal												
Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	· · /	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALS873BDWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS873BDWR	SOIC	DW	24	2000	367.0	367.0	45.0

MECHANICAL DATA

MCER004A - JANUARY 1995 - REVISED JANUARY 1997

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



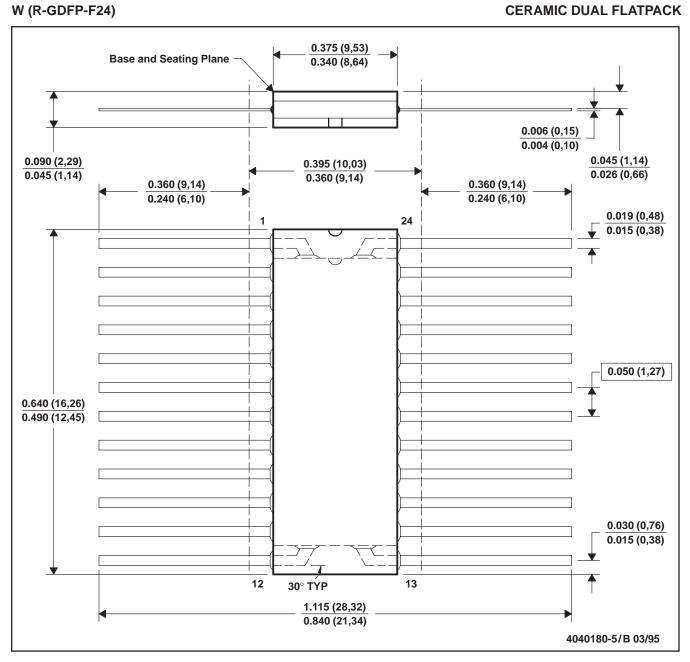
NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



MECHANICAL DATA

MCFP007 - OCTOBER 1994



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a ceramic lid using glass frit.

- D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
- E. Index point is provided on cap for terminal identification only.



LEADLESS CERAMIC CHIP CARRIER

FK (S-CQCC-N**) 28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. This package can be hermetically sealed with a metal lid.

D. Falls within JEDEC MS-004



NT (R-PDIP-T**) 24 pins shown

PLASTIC DUAL-IN-LINE PACKAGE



All integrations are in minimeters. Dimensioning and toil
B. This drawing is subject to change without notice.

The 28 pin end lead shoulder width is a vendor option, either half or full width.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-013 variation AD.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconne	ectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated